

GAU 2814
#818
a/g/a

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Konecni et al.

Serial No.: 08/988,686

Filed: 12/11/97

For: **METHOD AND SYSTEM FOR SELECTIVELY COUPLING A CONDUCTIVE MATERIAL TO A SURFACE OF A SEMICONDUCTOR DEVICE**



Docket No.: TI-22166

Art Unit: 2814

Examiner: Eaton, K.

Assistant Commissioner for
Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

August 30, 1999

Jeff Quan

AMENDMENT UNDER 37 CFR 1.115

Dear Sir:

In response to the Office Action mailed May 28, 1999, and in connection with the above-identified application, Applicant respectfully submits the following remarks and amendments. Please charge any necessary fees to the deposit account of Texas Instruments, Inc., Deposit Account No. 20-0668.

In the Title:

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TI-22166

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